

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHEK C. HONG	08/14/2017
RECEIVING PARTY DATA	
Name:	HONTEK CORPORATION
Street Address:	161 SOUTH SATELLITE ROAD
City:	SOUTH WINDSOR
State/Country:	CONNECTICUT
Postal Code:	06074
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15676212
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 4:	MIDDLETOWN, CONNECTICUT 06457
ATTORNEY DOCKET NUMBER:	1135-0001-3DIV-CON
NAME OF SUBMITTER:	MICHAEL K. KINNEY
SIGNATURE:	/Michael K. Kinney/
DATE SIGNED:	08/14/2017
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated below my names, am an inventor of certain new and useful improvements in EROSION RESISTANT COATING, for which a non-provisional application is being filed concurrently herewith, which is a continuation of U.S. Patent Application No. 14/052,035, filed on October 11, 2013, which is a division of U.S. Patent Application No. 12/815,963, filed on June 15, 2010, and issued as U.S. Patent No. 8,557,388 on October 15, 2013, which is a continuation of U.S. Patent Application No. 11/136,827, filed on May 24, 2005, and issued as U.S. Patent No. 7,736,745 on June 15, 2010, which claims the benefit of U.S. Provisional Application No. 60/573,819, filed on May 24, 2004, and U.S. Provisional Application No. 60/649,443, filed on February 2, 2005.

WHEREAS, I possess the entire right, title and interest in the foregoing invention, free from all encumbrances, and have full right to convey his part or all of his interest, and

WHEREAS, Hontek Corporation (hereinafter referenced as ASSIGNEE), a Connecticut corporation, having a place of business at 161 South Satellite Road, South Windsor, Connecticut 06074, is desirous of acquiring all rights, title and interest in, to and under said inventions, said applications disclosing the inventions and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole inventor, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the full, exclusive and entire right, title and interest in the said inventions, said applications, and any divisions, continuations and reissues thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and the right to sue and collect damages for past infringement, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

AND I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors,

Docket Number: 1135-0001-3DIV-CON

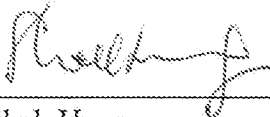
assigns and legal representatives may from time to time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

AND I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reexaminations, reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

AND I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any reexamination, interference or litigation related thereto;

AND I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

Witness



Shek Hong
212 Knollwood Drive
Glastonbury, Connecticut 06033

8/14/2017
Date

Witness